

SOT1916-1
FBGA609, fine-pitch ball grid array package; 609 terminals,
0.8 mm pitch, 21 mm x 21 mm x 2.37 mm body
26 June 2019
Package information

Package information

Package summary

Terminal position code B (bottom)

FBGA609 Package type descriptive code

Package style descriptive code FBGA (fine-pitch ball grid array)

Mounting method type S (surface mount)

Issue date 04-06-2019 Manufacturer package code 98ASA01051D

Table 1. Package summary

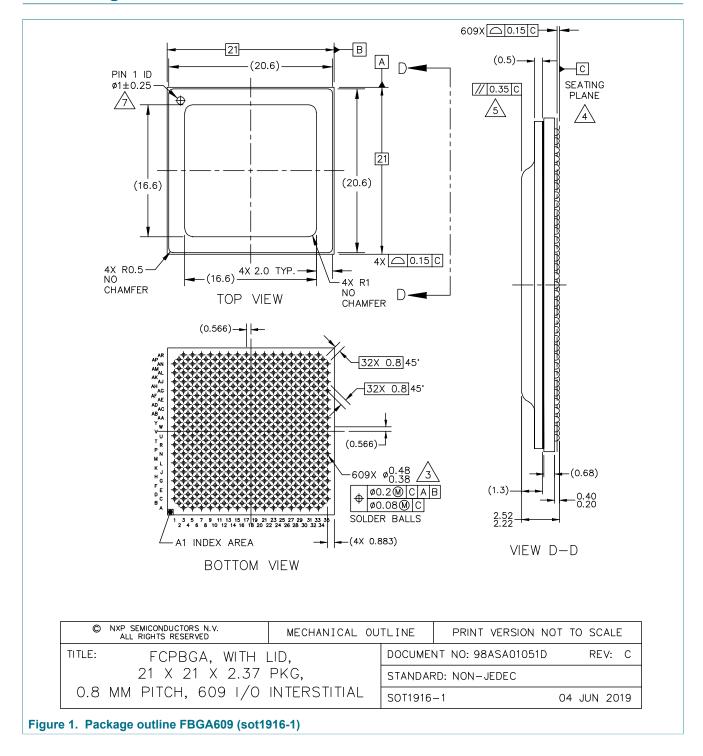
Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
seated height	-	2.37	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	609	-	



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2 Package outline



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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

 $\sqrt{3}$.\ MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.



DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE

 $\sqrt{7}$. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.

8. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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TITLE:	FCPBGA, WITH I	LID,	DOCUMEN	T NO: 98ASA01051D	REV: C
	21 X 21 X 2.37 PKG,		STANDAR	D: NON-JEDEC	
0.8	MM PITCH, 609 I/O	INTERSTITIAL	SOT1916-	-1	04 JUN 2019

Figure 2. Package outline note FBGA609 (sot1916-1)

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3 Legal information

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Contents

1	Package summary1
2	Package outline2
3	Legal information4